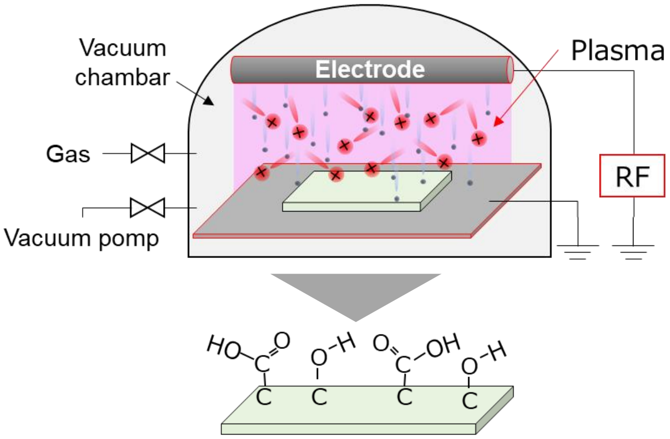
5G/6G base stations
mmWave antenna modules
Satellite Communications (Ka-Band)

No Roughening.
No Adhesive.
Low Loss at High Frequencies

77–81 GHz Automotive Radar
Phased-array radar systems
Aerospace RF Modules
AI data centers

MILD-PLASMA ™ Advanced Surface Activation Technology



Activation through surface functionalization

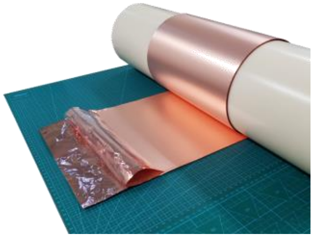
Four Key Advantages

1. Non-Roughening Surface Activation of Difficult-to-Bond Materials
2. Chemical Adhesion via Surface Functionalization
3. Long-Term Stability without Aging
4. Roll-to-Roll Mass Production Capability

Application Examples in Manufacturing Processes

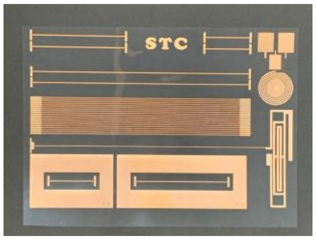
Low-Dielectric CCL

Adhesive-Free and Mechanical-Anchor-Free Bonding



Printed electronics on Low-Dielectric Materials

Adhesive-Free and Mechanical-Anchor-Free Bonding



Low-Dielectric Prepreg

Surface Activation of Glass Cloth for Improved Resin Impregnation

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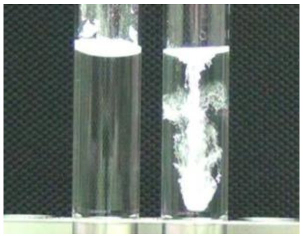
Thermal Interface Material (TIM)

Enhanced Filler–Resin Interfacial Adhesion
for Improved Thermal Performance



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